



P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)			
- 30	0.0068 at V _{GS} = - 10 V	- 22			

FEATURES

- TrenchFET[®] Power MOSFETS
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07 mm Profile



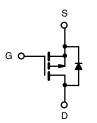
APPLICATIONS

- · Battery and Load Switching
 - Notebook Computers
 - Notebook Battery Packs

PowerPAK SO-8

Bottom View

Ordering Information: Si7459DP-T1-E3 (Lead (Pb)-free)



P-Channel MOSFET

Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	- 30		V	
Gate-Source Voltage		V_{GS}	± 25		V	
Continuous Drain Current (T _J = 150°C) ^a	T _A = 25 °C	I _D	- 22	- 13	۸	
	T _A = 70 °C		- 17	- 10		
Pulsed Drain Current		I _{DM}	- 60		Α	
Continuous Source Current (Diode Conduction) ^a		I _S	- 4.5	- 1.6		
Maximum Power Dissipation ^a	T _A = 25 °C	P _D	5.4	1.9	W	
	T _A = 70 °C		3.4	1.2	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature)b,c			260		C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	- R _{thJA}	18	23		
	Steady State		52	65	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.0	1.5	1	

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

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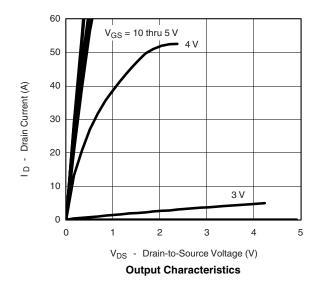
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static			L				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.0		- 3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	± 20 V		± 100	nA	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$		± 200			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	-		- 1		
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 \text{ °C}$			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = - 10 V, I _D = - 22 A		0.0056	0.0068	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 22 A		50		S	
Diode Forward Voltage ^a	V_{SD}	I _S = - 2.9 A, V _{GS} = 0 V		- 0.71	- 1.1	V	
Dynamic ^b							
Total Gate Charge	Q_g			113	170	nC	
Gate-Source Charge	Q_{gs}	V_{DS} = - 15 V, V_{GS} = - 10 V, I_D = - 22 A		17			
Gate-Drain Charge	Q_{gd}			32.5			
Turn-On Delay Time	t _{d(on)}			25	40		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 15 Ω		20	30	- ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_G = 6 Ω		180	270		
Fall Time	t _f			130	200		
Gate Resistance	R_{g}			4		Ω	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 2.9 A, di/dt = 100 A/μs		100	150	ns	

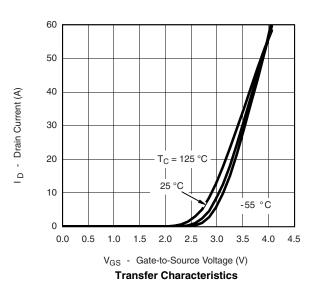
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



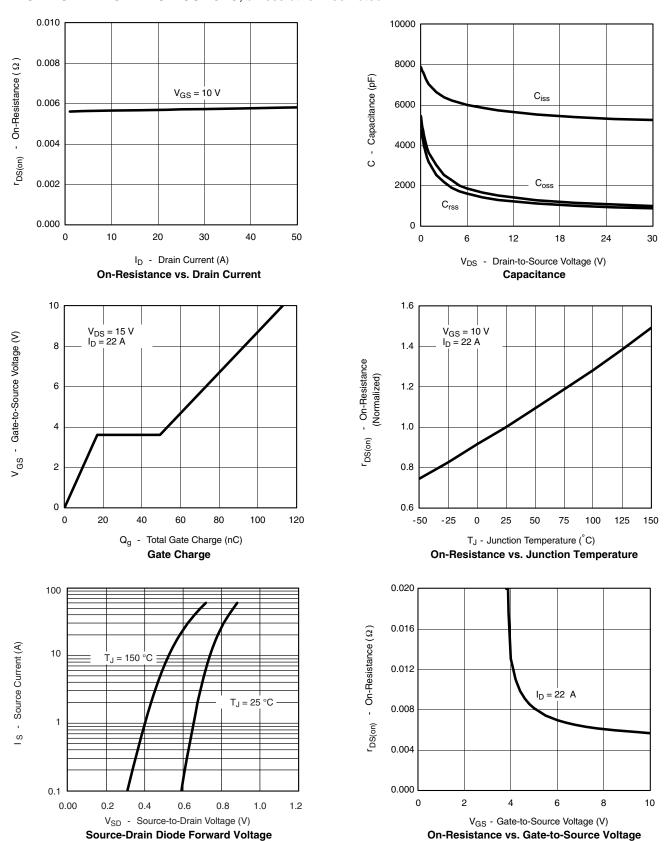








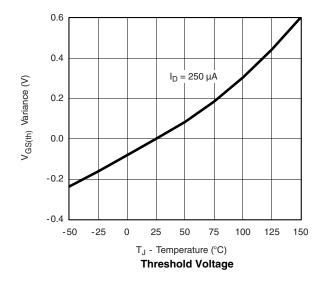
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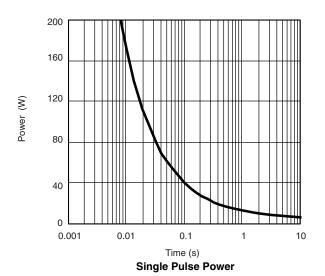


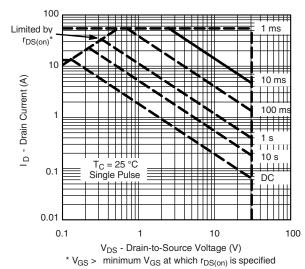
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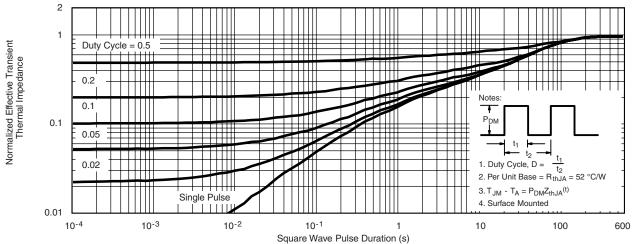
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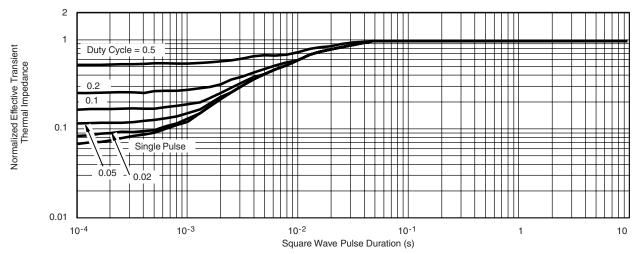
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72631.

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